

FEB 11 2004

BY TELEFAX TO:
(703) 872-9306
=====**OFFICIAL****EXPEDITED PROCEDURE**
RESPONSE UNDER 37 CFR 1.116
EXAMINING GROUP: 1722
BOX AF

DOCKET NO.: 4029

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE MATTER OF THE APPLICATION FOR PATENT

OF: Michio OSADA et al.	Art Unit: 1722
SERIAL NO.: 09/705,237	Confirmation No.: 4586
FILED: November 2, 2000	EX.: Thukhanh T. Nguyen
FOR: Die Used for Resin-Sealing and Molding an Electronic Component	

MS AF
 COMMISSIONER FOR PATENTS
 P.O. BOX 1450
 ALEXANDRIA, VA 22313-1450

February 9, 2004

RESPONSE TO THE FINAL OFFICE ACTION OF DECEMBER 9, 2003 INCLUDING
 AN ATTACHED COVER SHEET WITH CERTIFICATE OF TELEFAX TRANSMISSION

Dear Sir:

This Response should receive expedited handling because it is being filed within **TWO MONTHS** after the mailing date of the Final Office Action on December 9, 2003.

Please amend the above identified application as follows.

4029/WFF:ar

- 1 -